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# IGBT 600V, 10A, N-Channel

#### **Features**

- Reverse Conducting II IGBT
- IGBT VCE(sat)=1.7V (typ) [IC=10A, VGE=15V]
- IGBT tf=65ns (typ)
- Diode V<sub>F</sub>=1.5V (typ) [I<sub>F</sub>=10A]
- Diode t<sub>rr</sub>=90ns (typ)
- 5µs Short Circuit Capability

### **Applications**

• General Purpose Inverter

#### **Specifications**

Absolute Maximum Ratings at Ta=25°C, Unless otherwise specified

Paramete	Parameter		Value	Unit
Collector to Emitter Voltage		VCES	600	V
Gate to Emitter Voltage		VGES	±20	V
Collector Current (DC)	@Tc=25°C *2	11	20	Α
Limited by Tjmax	@Tc=100°C *2	IC *1	10	Α
Collector Current (Peak)		1	40	А
Pulse width Llimited by Tjma	ICP	40	A	
Diode Average Output Curre	ent	I <sub>O</sub>	10	А
Power Dissipation		D-	70	14/
Tc=25°C (Our ideal heat dissi	PD	72	W	
Junction Temperature	Tj	175	°C	
Storage Temperature	Tstg	–55 to +175	°C	

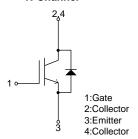
Note: \*1 Collector Current is calculated from the following formula.

$$I_{C}(\text{Tc}) = \frac{\text{Tjmax - Tc}}{R_{th}(\text{j-c}) \times V_{CE}(\text{sat}) (I_{C}(\text{Tc}))}$$

\*2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.

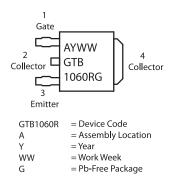
## Electrical Connection N-Channel





DPAK CASE 369C

### **Marking Diagram**



Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

#### Electrical Characteristics at Ta=25°C, Unless otherwise specified

Description	Oh. al	Conditions		Value			
Parameter	Symbol			min	typ	max	Unit
Collector to Emitter Breakdown Voltage	V(BR)CES	I <sub>C</sub> =1mA, V <sub>GE</sub> =0V		600			٧
0.11.1.1.5.11.0.1.11.0	ICES	V <sub>CE</sub> =600V, V <sub>GE</sub> =0V	Tc=25°C			10	μА
Collector to Emitter Cut off Current			Tc=150°C			1	mA
Gate to Emitter Leakage Current	IGES	V <sub>GE</sub> =±20V, V <sub>CE</sub> =0V				±100	nA
Gate to Emitter Threshold Voltage	V <sub>GE</sub> (th)	V <sub>CE</sub> =20V, I <sub>C</sub> =160μA		4.5		7.0	٧
Callantanta Fasittan Catamatian Valtana		V 45V 1 404	Tc=25°C		1.7	2.1	V
Collector to Emitter Saturation Voltage	VCE(sat)	V <sub>GE</sub> =15V, I <sub>C</sub> =10A	Tc=100°C		1.9	2.3	٧
Forward Diode Voltage	VF	I <sub>F</sub> =10A			1.5	2.1	>
Input Capacitance	Cies	V <sub>CE</sub> =20V, f=1MHz			1340		pF
Output Capacitance	Coes				45		pF
Reverse Transfer Capacitance	Cres				33		pF
Turn-ON Delay Time	t <sub>d</sub> (on)	V <sub>CC</sub> =300V, I <sub>C</sub> =10A R <sub>G</sub> =30Ω, L=500μH V <sub>GE</sub> =0V/15V Vclamp=400V T <sub>C</sub> =25°C See Fig.1, See Fig.2			48		ns
Rise Time	t <sub>r</sub>				34		ns
Turn-ON Time	ton				188		ns
Turn-OFF Delay Time	t <sub>d</sub> (off)				120		ns
Fall Time	tf				65		ns
Turn-OFF Time	toff				220		ns
Turn-ON Energy	Eon				412		μJ
Turn-OFF Energy	Eoff				140		μJ
Total Gate Charge	Qg	V <sub>CE</sub> =300V, V <sub>GE</sub> =15V, I <sub>C</sub> =10A  I <sub>F</sub> =10A,di/dt=300A/µs, V <sub>CC</sub> =300V, See Fig.3			53		nC
Gate to Emitter Charge	Qge				10		nC
Gate to Collector "Miller" Charge	Qgc				25		nC
Diode Reverse Recovery Time	t <sub>rr</sub>				90		ns

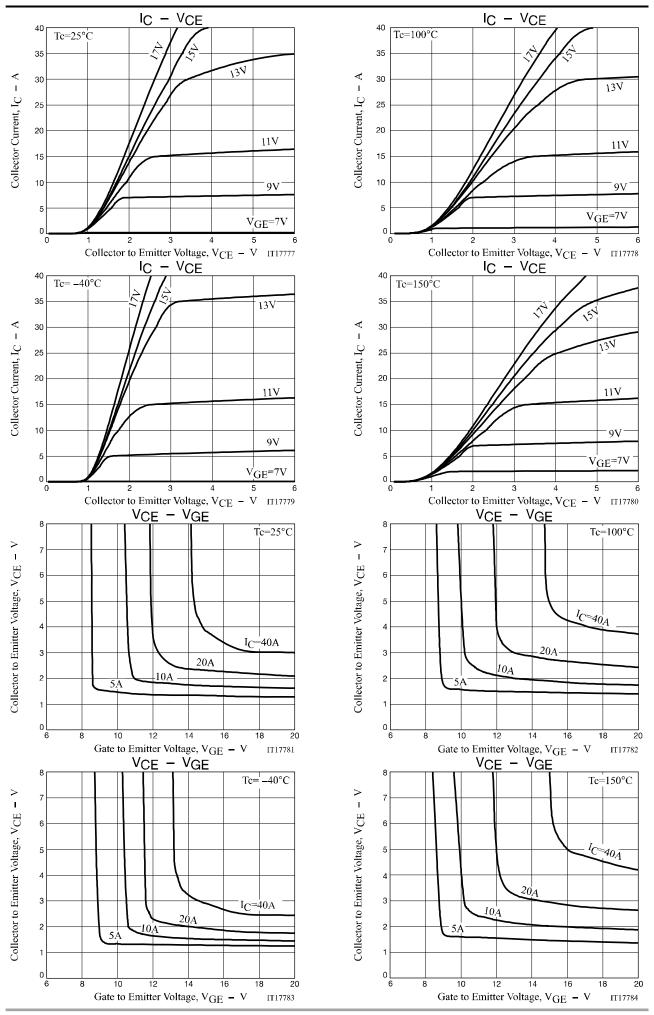
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

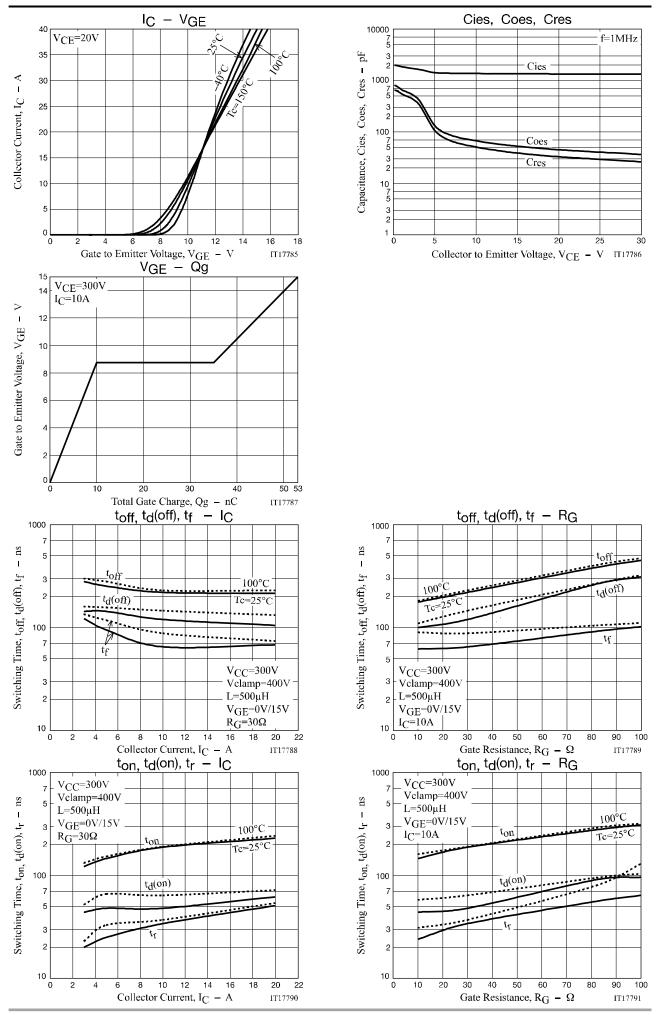
#### Thermal Characteristics at Ta=25°C, Unless otherwise specified

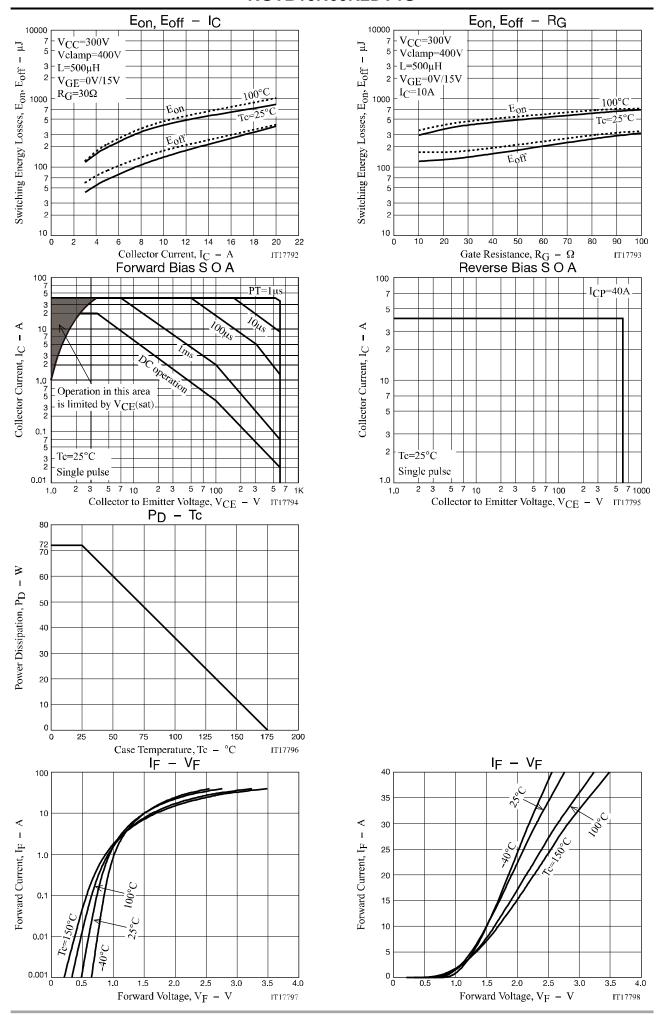
Parameter	Symbol	Conditions	Value	Unit
Thermal Resistance IGBT (Junction to Case)	Rth(j-c) (IGBT)	Tc=25°C (Our ideal heat dissipation condition) *2	2.07	°C/W
Thermal Resistance (Junction to Ambient)	Rth(j-a)		100	°C/W

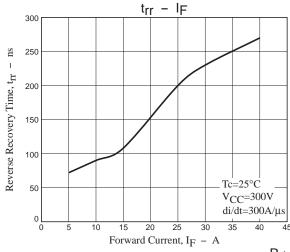
Note: \*2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.









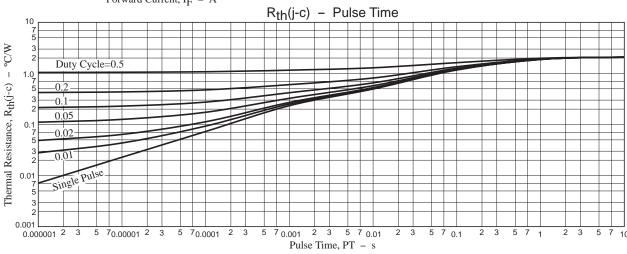


Fig.1 Switching Time Test Circuit

NGTB10N60R2DT4G

RG

W

WCC

**Fig.2 Timing Chart** 

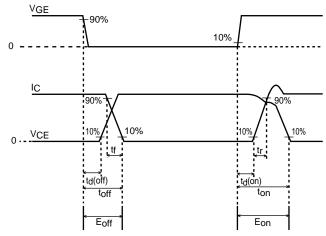
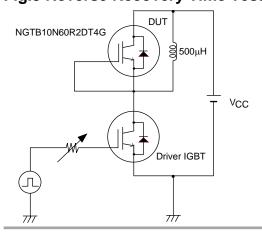


Fig.3 Reverse Recovery Time Test Circuit

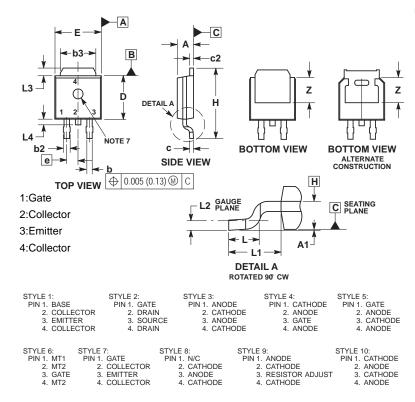


#### **Package Dimensions**

unit: mm

**DPAK (SINGLE GAUGE)** 

CASE 369C ISSUE E

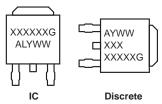


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- THERMAL PAD CONTOUR OPTIONAL WITHIN
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
  6. DATUMS A AND B ARE DETERMINED AT DATUM PI ANE

- OPTIONAL MOLD FEATURE

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29	BSC	
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114 REF		2.90 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

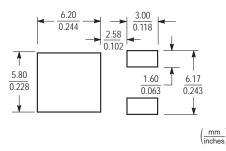
#### **GENERIC MARKING DIAGRAM\***



XXXXXX = Device Code = Assembly Location Α = Wafer Lot L = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### ORDERING INFORMATION

Device	Package	Shipping	note
NGTB10N60R2DT4G	DPAK	2500 pcs. / reel	Pb-Free And Halogen Free

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 VS-CPV364M4KPBF
 NGTB25N120FL2WAG
 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

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 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
 IKFW40N65ES5XKSA1

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 FGH60N60SMD\_F085

 FGH75T65UPD
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 IKA10N60TXKSA1
 IHW20N120R5XKSA1
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 IKP20N60TXKSA1

 IHW20N65R5XKSA1
 IDW40E65D2FKSA1